

Position	Component Structure Drawings	Wight (mg)	Material group
1	Chip	0.8102	Si
2	Bonding wire	0.0187	Cu Alloy
3	Lead Frame	3.1695	Ni,Fe
4	Epoxy Molding	4.0165	Epoxy Resin
5	Tin ingot	0.0845	Sn
	Total wight(mg)	8.10	

Chemical Element substance name	Chemical Element substance Weight Percentage(wt%)	CAS no#	Wight (mg)
Si	98.00%	7440-21-3	0.8102
Ti	0.01%	7440-32-6	
Ni	0.01%	7440-02-0	
Ag	1.97%	7440-22-4	
Au	0.01%	7740-57-5	
Cu	100.00%	7440-50-8	0.0187
Ni	40.84%	7440-02-0	3.1695
Fe	54.66%	7439-89-6	
Ag	4.50%	7440-22-4	
Silica	75.00%	7631-86-9	4.0165
Epoxy Resin	15.00%	24969-06-0	
Phenol Resin	8.00%	9003-35-4	
Zinc Borate	1.95%	12513-27-8	
Carbon BLACK	0.05%	1333-86-4	
Sn	100.00%	7440-31-5	0.0845